

# **Description**

The VSM6003Y uses advanced trench technology to provide excellent  $R_{\rm DS(ON)}$ , low gate charge and operation with gate voltages as low as 2.5V. This device is suitable for use as a Battery protection or in other switching application.

#### **General Features**

V<sub>DS</sub> =60V,I<sub>D</sub> =3A

 $R_{DS(ON)}$  <105m $\Omega$  @  $V_{GS}$ =10V

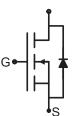
 $R_{DS(ON)}$  < 125m $\Omega$  @  $V_{GS}$ =4.5V

- High power and current handing capability
- Lead free product is acquired
- Surface mount package

## **Application**

- Battery switch
- ●DC/DC converter





SOT-23-3

Schematic Diagram

#### **Package Marking and Ordering Information**

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
VSM6003Y-S2	VSM6003Y	SOT-23-3	Ø180mm	8 mm	3000 units

## Absolute Maximum Ratings (T<sub>A</sub>=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V <sub>DS</sub>	60	V
Gate-Source Voltage	V <sub>G</sub> S	±20	V
Drain Current-Continuous	I <sub>D</sub>	3	Α
Drain Current-Pulsed (Note 1)	I <sub>DM</sub>	10	Α
Maximum Power Dissipation	P <sub>D</sub>	1.7	W
Operating Junction and Storage Temperature Range	$T_{J}, T_{STG}$	-55 To 150	℃

#### **Thermal Characteristic**

Thermal Resistance, Junction-to-Ambient (1982)		$R_{\theta JA}$		°C/W
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## Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Тур	Max	Unit		
Off Characteristics								
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	60	65	-	V		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> =60V,V <sub>GS</sub> =0V	-	-	1	μΑ		



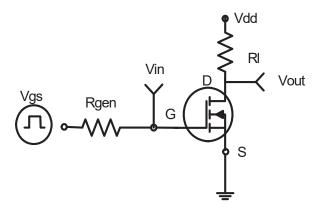
Gate-Body Leakage Current	I <sub>GSS</sub>	$V_{GS}$ =±20 $V$ , $V_{DS}$ =0 $V$	-	-	±100	nA
On Characteristics (Note 3)			•			
Gate Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS}=V_{GS},I_{D}=250\mu A$	0.8	1.3	2.0	V
Drain-Source On-State Resistance	D	V <sub>GS</sub> =10V, I <sub>D</sub> =3A	-	78	105	mΩ
	R <sub>DS(ON)</sub>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =3A	-	95	125	mΩ
Forward Transconductance	<b>g</b> FS	$V_{DS}=5V,I_{D}=3A$	4	-	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C <sub>lss</sub>	V <sub>DS</sub> =30V,V <sub>GS</sub> =0V, F=1.0MHz	-	510	-	PF
Output Capacitance	Coss		-	34	-	PF
Reverse Transfer Capacitance	C <sub>rss</sub>	r-1.0ivinz	-	26	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> =30V,I <sub>D</sub> =3A	-	6	-	nS
Turn-on Rise Time	t <sub>r</sub>		-	15	-	nS
Turn-Off Delay Time	t <sub>d(off)</sub>	$V_{GS}$ =10 $V$ , $R_{GEN}$ =1 $\Omega$	-	15	-	nS
Turn-Off Fall Time	t <sub>f</sub>		-	10	-	nS
Total Gate Charge	Qg	V <sub>DS</sub> =30V,I <sub>D</sub> =3A,	-	14.6	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	1.6	-	nC
Gate-Drain Charge	Q <sub>gd</sub>	V <sub>GS</sub> =10V	-	3	-	nC
Drain-Source Diode Characteristics						-
Diode Forward Voltage (Note 3)	V <sub>SD</sub>	$V_{GS}$ =0 $V$ , $I_{S}$ =3 $A$	-	-	1.2	V
Diode Forward Current (Note 2)	Is		-	-	3	Α

## Notes:

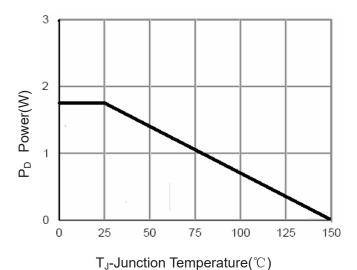
- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
  3. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2%.
- **4.** Guaranteed by design, not subject to production



# **Typical Electrical and Thermal Characteristics**



**Figure 1:Switching Test Circuit** 



**Figure 3 Power Dissipation** 

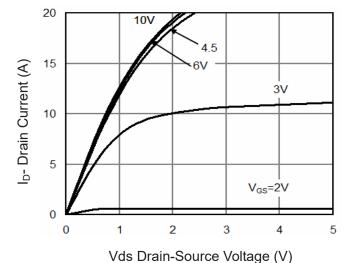


Figure 5 Output Characteristics

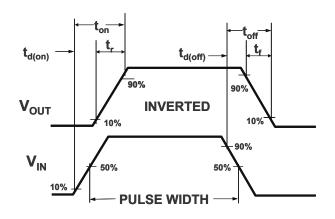
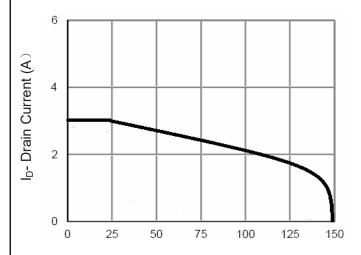


Figure 2:Switching Waveforms



T<sub>J</sub>-Junction Temperature(°C)

Figure 4 Drain Current

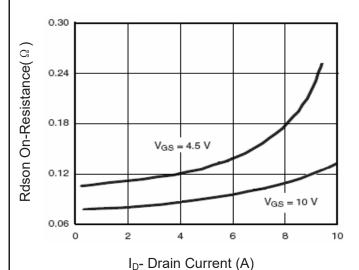
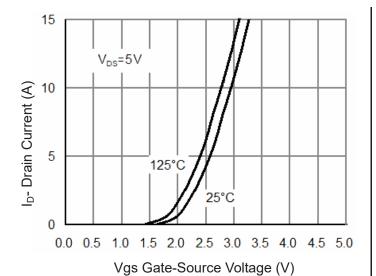
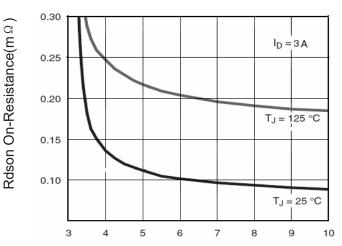


Figure 6 Drain-Source On-Resistance



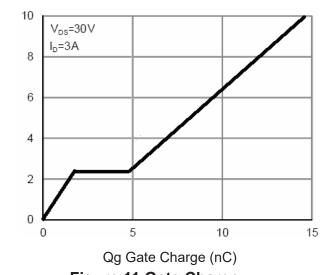


**Figure 7 Transfer Characteristics** 



Vgs Gate-Source Voltage (V)

Figure 9 Rdson vs Vgs



Vgs Gate-Source Voltage (V)

Figure 11 Gate Charge

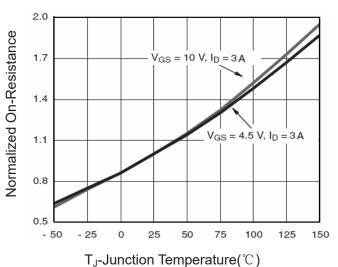


Figure 8 Drain-Source On-Resistance

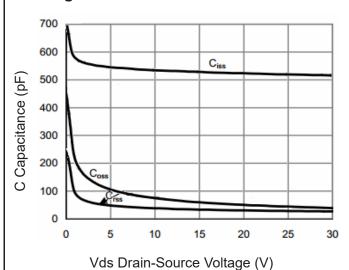


Figure 10 Capacitance vs Vds

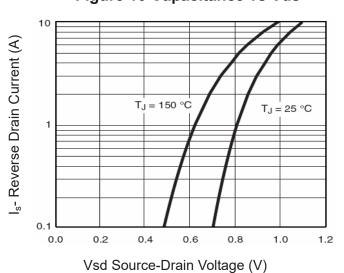
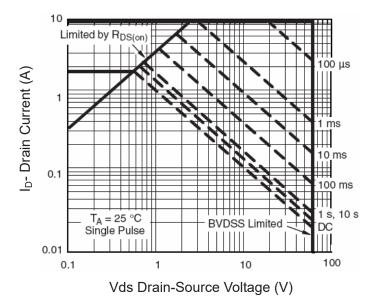
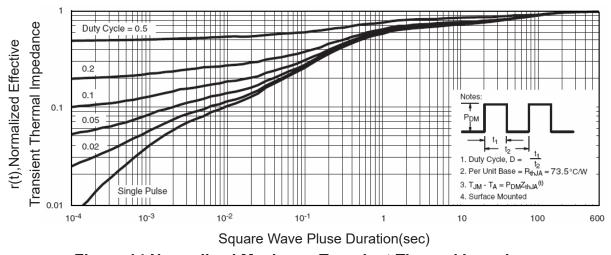


Figure 12 Source- Drain Diode Forward





**Figure 13 Safe Operation Area** 



**Figure 14 Normalized Maximum Transient Thermal Impedance**